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IN THE U.S. PATENT AND TRADEMARK OFFICE

Applicant: Shoichi OSADA et al. Conf.: 9440
Appl. No.: 09/883,276 Group: 1712
Filed: June 19, 2001 Examiner: Marc ZIMMER
For: SEMICONDUCTOR ENCAPSULATING EPOXY RESIN
COMPOSITION AND SEMICONDUCTOR DEVICE

AMENDMENT UNDER 37 C.F.R. 1.111

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

July 1, 2003

Sir:

In reply to the Office Action of April 1, 2003, the following amendments and Remarks are respectfully submitted in connection with the above-identified application.

This Paper includes:

Amended Claim Set;
Remarks; and
Declaration of Shoichi Osada.

The amendments presented herein comply with the "Revised Amendment Format" as set forth in the Official Gazette Notice dated February 25, 2003. In accordance with the Notice, therefore, the provisions of 37 CFR 1.121 (a)-(d) are waived.